
Polprevodniški elementi - Mikroelektromehanski elementi - 15. del: Metoda za preskušanje spojne trdnosti med PDMS in steklom

Semiconductor devices - Micro-electromechanical devices - Part 15: Test method of bonding strength between PDMS and glass

Halbleiterbauelemente - Bauelemente der Mikrosystemtechnik - Teil 15: Prüfverfahren zur Bondqualität zwischen PDMS und Glas

Dispositifs à semiconducteurs - Dispositifs microélectromécaniques - Partie 15: Méthode d'essai de la résistance de collage entre PDMS et verre

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Ta slovenski standard je istoveten z: EN 62047-15:2015

ICS:

31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
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SIST EN 62047-15:2015**en**

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Semiconductor devices - Micro-electromechanical devices - Part 15: Test method of bonding strength between PDMS and glass (IEC 62047-15:2015)

Dispositifs à semiconducteurs - Dispositifs microélectromécaniques - Partie 15: Méthode d'essai de la résistance de collage entre PDMS et verre
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Halbleiterbauelemente - Bauelemente der Mikrosystemtechnik - Teil 15: Prüfverfahren zur Bondqualität zwischen PDMS und Glas
(IEC 62047-15:2015)

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Europäisches Komitee für Elektrotechnische Normung

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EN 62047-15:2015**European foreword**

The text of document 47F/208/FDIS, future edition 1 of IEC 62047-15, prepared by SC 47F "Microelectromechanical systems" of IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-15:2015.

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- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2016-01-10
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Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-9	-	Semiconductor devices - Micro-electromechanical devices -- Part 9: Wafer to wafer bonding strength measurement for MEMS	EN 62047-9	-

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**Semiconductor devices – Micro-electromechanical devices –
Part 15: Test method of bonding strength between PDMS and glass**

**Dispositifs à semiconducteurs – Dispositifs microélectromécaniques –
Partie 15: Méthode d'essai de la résistance de collage entre PDMS et verre**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –

**Part 15: Test method of bonding
strength between PDMS and glass**

FOREWORD

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International Standard IEC 62047-15 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/208/FDIS	47F/213/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.